IV. AMENDMENTS TO THE CLAIMS

1. (Currently Amended) An ultraviolet irradiating method for emitting ultraviolet light toward a work piece and a frame holding said work piece through an ultraviolet sensitive adhesive tape applied to a back surface of the work piece, said method comprising:

a step of placing a regulating member ~~as spaced downward from the work piece held by~~ separate from the adhesive tape applied to the back surface of the work piece, with a predetermined gap downward from a back surface of the adhesive tape prior to emitting ultraviolet light;

a step of emitting ultraviolet light to said work piece; and

a step of ~~supporting~~ stopping, with said regulating member, ~~an under-surface of said work piece held by said frame when the adhesive tape softens under influence of heat in the step of emitting ultraviolet light and slackening under weight of the work piece~~the adhesive tape and the work piece closing said gap formed between the back surface of the adhesive tape and the regulating member and falling as a result of the adhesive tape softening and slackening under influence of heat, and the adhesive tape and the work piece falling together under weight of the work piece, in the step of emitting ultraviolet light.

2. (Original) An ultraviolet irradiating method as defined in claim 1, wherein said frame is a ring-shaped frame having an inside diameter of at least 300mm.

3. (Original) An ultraviolet irradiating method as defined in claim 1, wherein said work piece is a semiconductor wafer, glass component or semiconductor package substrate.

4. (Currently Amended) An ultraviolet irradiating apparatus for emitting ultraviolet light toward a work piece and a ring-shaped frame holding said work piece through an ultraviolet sensitive adhesive tape

applied to a back surface of the work piece, said apparatus comprising:

regulating means disposed at a predetermined distance from a back surface of said adhesive tape ~~for limiting a downward displacement of said work piece held by said ring-shaped frame when emitting ultraviolet light toward said work piece~~, prior to emitting ultraviolet light, for stopping the adhesive tape and the work piece closing said gap formed between the back surface of the adhesive tape and the regulating member and falling as a result of the adhesive tape softening and slackening under influence of heat, and the adhesive tape and the work piece falling together under weight of the work piece, during an ultraviolet light emission toward said work piece.

5. (Original) An ultraviolet irradiating apparatus as defined in claim 4, wherein a distance from an undersurface of said work piece to said regulating means is set to at most 3mm.

6. (Original) An ultraviolet irradiating apparatus as defined in claim 4, wherein said regulating means is formed of glass plate.

7. (Previously Presented) An ultraviolet irradiating apparatus as defined in claim 6, wherein said glass plate comprises soda glass or borosilicate glass.

8. (Original) An ultraviolet irradiating apparatus as defined in claim 7, wherein said glass plate has a thickness of at least 100μm.

9. (Original) An ultraviolet irradiating apparatus as defined in claim 4, wherein said regulating means is formed of a plastic penetrable by ultraviolet light.

10. (Original) An ultraviolet irradiating apparatus as defined in claim 9, wherein said plastic is a polyester film or polyester sheet.

11. (Original) An ultraviolet irradiating apparatus as defined in claim 10, wherein said polyester film or polyester sheet has a thickness of at least 150μm.

12. (Original) An ultraviolet irradiating apparatus as defined in claim 4, wherein said regulating means is formed of metal wires arranged in a grid.

13. (Original) An ultraviolet irradiating apparatus as defined in claim 12, wherein said metal wires arranged in a grid have a thickness of at most 0.5mm, and have intervals therebetween of at most 20mm.

14. (Original) An ultraviolet irradiating apparatus as defined in claim 4, wherein said regulating means is formed of a cold filter.

15. (Original) An ultraviolet irradiating apparatus as defined in claim 4, wherein said work piece is a semiconductor wafer, glass component or semiconductor package substrate.